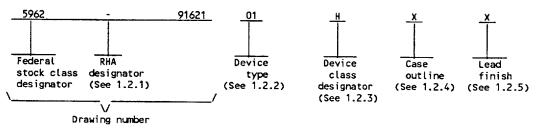
,

											RE	VIS	IONS	8												
LTR								DES	CRIP	TION			_						DAT	Ë (YF	R-MO-	DA)	4	PPR	OVED)
REV	1		Τ																		Γ					
SHEET																										-
REV																										
SHEET																										<u> </u>
REV STA			RE	<u>v</u>																						
OF SHE	ETS		SHE	EET		1	2	3	4	5	6	7	8	9	10	11										
		۱R	1)	- <u> </u> _			an	1	2	an La	6	r 					DA	YTO!	4, OH	10 4	5444			۹ 	
THIS DRA FOR USE B AND A DEPART AMSC 1	Y ALL GENCI MENT	DEP/	ARTM F THE	ENTS E	Ĺ	9) <u>}-(</u>		15					1-	size A		é	age (CODE 68			596	52-	916	521	
DESC FORM SEP 87	4 193													<u>I_</u>	-	HE	-		1 	-				187 — 7 278	48-129	v6091
DISTRI	BUTIC	N S	TATE	MEN	ΤΑ.	Ар	prove	ed for		lic re] [] [] []																

11月 3902-9102101日XA 洪沙商

1.1 Scope. This drawing forms a part of a one part - one part number documentation system (see 6.6). This drawing describes device requirements for hybrid microcircuits to be processed in accordance with MIL-H-38534. Two product assurance classes, military high reliability (device class H) and space application (device class K) and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.

1.2 PIN. The PIN shall be as shown in the following example:



1.2.1 Radiation hardness assurance (RHA) designator. Device classes H and K RHA marked devices shall meet the MIL-H-38534 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	PA83M/883	Power operational amplifier

Power operational amplifier

1.2.3 Device class designator. This device class designator shall be a single letter identifying the product assurance level as follows:

Device class	Device requirements documentation
H or K	Certification and qualification to MIL-H-38534

1.2.4 <u>Case outline(s)</u>. The case outline(s) shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter

X

Case outline

See figure 1, TO-3 (8-lead) can package

1.2.5 Lead finish. The lead finish shall be as specified in MIL-H-38534 for classes H and K. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

1.3 Absolute maximum ratings.

- -

Supply voltage (V _S) Sutput current (I _O)			-						 _	-	_	-	+150 V dc
Output current (I_{a}^{S})			-		• -		. <u>-</u>	-	 		-	-	100 mA
Power dissipation (P_) 1/			-					-	 •	-	-	-	175 บ
input voltage (diffeřential) -			-	• •	• •		-	-	 -	•	-	•	±300 V dc
nput voltage (common-mode)			-		• •	• •	-	-	 -	-	-	-	±300 V dc
ead temperature (soldering, 1	10 seco), nds	-				•	-	 -	-	-	-	+300°C
lunction temperature (1) Storage temperature range	•		-		-		-	•	 -	-	•	-	+150°C
Storage temperature ranĝe			-		• •		-	-	 •	-	•	-	-65°C to +150°C
Case operating temperature rang	;е (т _с)		-			• -	-	-	 -	-	-	-	-55°C to +125°C

<u>1</u>/ Derate at 6.5°C/W above $T_{C} = +25°C$.

STANDARDIZED MILITARY DRAWING			size A		5962-91621			
		ELECTRONICS SUPP DAYTON, OHIO 4544			REVISION LEVEL	SHEET	2	
DESC SEP	FORM 193, 87	Ą	900470	A 0026	329 51 T	+ U S GOVERNMENT PRINT	NG OFFICE 1998-880-547	

🔲 9004708 0026329 51T 🔳

1.4 <u>Recommended operating conditions</u>.

2. APPLICABLE DOCUMENTS

2.1 <u>Government specifications, standards, and handbook</u>. Unless otherwise specified, the following specifications, standards, and handbook of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATIONS

MILITARY

MIL-N-38510 - Nicrocircuits, General Specification for. MIL-H-38534 - Hybrid Microcircuits, General Specificatio	for.
---------------------------------------------------------------------------------------------------------------------	------

STANDARDS

MILITARY

MIL-STD-480-Configuration Control-Engineering Changes, Deviations and Waivers.MIL-STD-883-Test Methods and Procedures for Microelectronics.

HANDBOOK

MILITARY

MIL-HDBK-780 - Standardized Military Drawings.

(Copies of the specifications, standards, and handbook required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-H-38534 and as specified herein.

3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-H-38534 and herein.

STANDARDIZED MILITARY DRAWING	size A		5962-91621		
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 3		
DESC FORM 193A 9004 SEP 87	708 002	6930 231 m	+ U & GOVERNMENT PRINTING OFFICE: 1888580-547		

3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 2.

3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.

3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 <u>Marking</u>. Marking shall be in accordance with MIL-H-38534. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in QML-38534.

3.6 <u>Manufacturer eligibility</u>. In addition to the general requirements of MIL-H-38534, the manufacturer of the part described herein shall submit for DESC-ECC review and approval electrical test data (variables format) on 22 devices from the initial quality conformance inspection group A lot sample, produced on the certified line, for each device type listed herein. The data should also include a summary of all parameters manually tested, and for those which, if any, are guaranteed.

3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance submitted to DESC-ECC shall affirm that the manufacturer's product meets the requirements of MIL-H-38534 and the requirements herein.

3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-H-38534 shall be provided with each lot of microcircuits delivered to this drawing.

4. QUALITY ASSURANCE PROVISIONS

4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-H-38534.

4.2 <u>Screening</u>. Screening shall be in accordance with MIL-H-38534. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

- Test condition D using the circuit submitted with the certificate of compliance (see 3.7 herein).
- (2) T_{C} as specified in accordance with table I of method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- c. Constant acceleration may be performed after burn-in upon approval by the qualifying activity.

4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with MIL-H-38534 and as specified herein.

STANDA MILITARY		size A		91621	
	NICS SUPPLY CENTER OHIO 45444		REVISION LEVEL		SHEET 4
DESC FORM 193A SEP 87	900470	8 002633;	1 178 🖬	+ U S GOVER	INMENT PRINTING OFFICE: 1888-880-547

٠

Test	Symbol	Conditions <u>1</u> /	Group A	Limi	ts	U
		-55°C ≤ T _C ≤ +125°C V _S = ±150 V dc unless otherwise specified	subgroups	Min	Max	
Supply current	^I s	V _{IN} = VCM = 0 V dc, G = 100,	1 2,3		8.5 10	r
Input offset voltage	v _{os}	V = 0 V dc, G = 100, V _S = ±15 V dc	1 2 3	-5.7 -8.2 -7.7	+8.2	n
		V _{IN} = 0 V dc, G = 100, V _S = ±150 V dc	1 2 3	-3.0 -5.5 -5.0	+5.5	រា
Input bias current, +IN	+1 _B	V _{IN} = 0 V dc, R _{BIAS} ≤ 100 MΩ	1,3		50.0	F
		BIAS - 100 Mar	2		10.0	r
Input bias current, -IN	- I _B	V _{IN} = 0 V dc, R _{BIAS} ≤ 100 MΩ	1,3		50.0	F
			2		10.0	n
Input offset current	Ios	V _{IN} = 0 V dc, R _{BIAS} ≤ 100 MΩ	1,3		50.0	p
		BIAS S 100 ML	2		10.0	r
Output voltage	v _o	$V_{s} = \pm 150 \text{ V dc}, I_{0} = 29 \text{ mA}, R_{L}^{S} = 5 \text{ k}\Omega$	4,5,6	145		v
		$V_{s} = \pm 45 V dc$, $I_{0} = 40 mA$, $R_{L}^{2} = 1 k\Omega$	5,6	40		v
		$V_{\rm S}$ = ±85 V dc, $I_{\rm O}$ = 75 mA, $R_{\rm L}^{\rm C}$ = 1 k Ω	4	75		v
STANDADDIZED	÷.	SIZE				
STANDARDIZED	IG	A	5962-	91621		
				the second s		

TABLE I. Electrical performance characteristics

Test	Symbol	Conditions <u>1</u> /	Group A	Lim	its	Unit
		-55°C ≤ T _C ≤ +125°C V _S = ±150 V dc unless otherwise specified	subgroups	Min	Max	
Current limits	^I CL	R _L = 100Ω, V _S = ±30 V dc	4	75	125	mΑ
Stability/noise	E _N	$G = 1, C_{L} = 10 \text{ nF}$	4,5,6		1.0	mV
Slew rate	s _R	R _L = 5 kΩ, V _{IN} ≥ 4 V _{P-P}	4,5,6	20	60	V/µs
Open loop gain	A _{OL}	R ₁ = 5 kΩ, f = 15 Hz, V ^L _{IN} ≥ .4 V _{P-P}	4,5,6	94		dB
Common mode rejection	CMR	$V_{S} = \pm 32.5 V dc, f = dc$ $V_{CM}^{S} = \pm 22.5 V dc$	4,5,6	90		dB

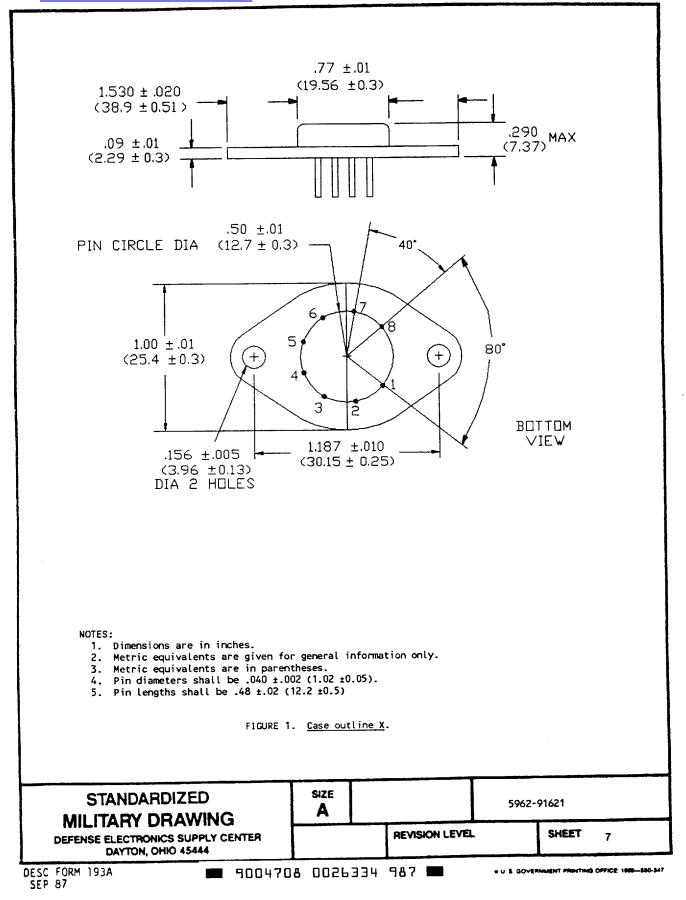
TABLE I. <u>Electrical performance characteristics</u> - Continued.

 $\underline{1}$ / During all group A testing, terminal connections BAL (pins 3 and 4) are left open.

4.3.1 Group A inspection. Group A inspection shall be in accordance with MIL-H-38534 and as follows:

- a. Tests shall be as specified in table II herein.
- b. Subgroups 7, 8, 9, 10, and 11 in table X, method 5008 of MIL-STD-883 shall be omitted.
- 4.3.2 <u>Group B inspection</u>. Group B inspection shall be in accordance with MIL-H-38534.
- 4.3.3 Group C inspection. Group C inspection shall be in accordance with MIL-H-38534 and as follows:
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - Test condition D using the circuit submitted with the certificate of compliance (see 3.7 herein).
 - (2) T_c as specified in accordance with table I of method 1005 of M1L-STD-883.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

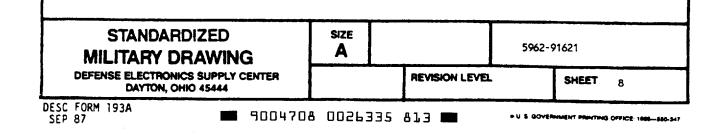
STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444			size A		5962·	-91621
				REVISION	LEVEL	SHEET 6
DESC FORM 193A SEP 87	9 00	34708	0056333	T40 🔳	+ u S 60v	ERNMENT PRINTING OPPICE: 1988\$80-547



Device type	01
Case outline	x
Terminal number	Terminal symbol
1	OUT
2	+v _s
3	BAL
4	BAL
5	- IN
6	+IN
7	-v _s
8	NC

.





MIL-STD-883 test requirements	Subgroups (per method 5008, group A test table)
Interim electrical parameters	
Final electrical test parameters	1*,2,3,4,5,6
Group A test requirements	1,2,3,4,5,6
Group C end-point electrical parameters	1,4
Group E end-point electrical parameters for RHA devices	Subgroups ** (per method 5005, group A test table)

TABLE II.	Electrical	test req	uirements.

*PDA applies to subgroup 1.

**When applicable to this standardized military drawing, the subgroups shall be defined.

4.3.4 Group D inspection. Group D inspection shall be in accordance with MIL-H-38534.

4.3.5 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes H and K shall be M, D, R, and H. RHA quality conformance inspection sample tests shall be performed at the RHA level specified in the acquisition document.

- a. RHA tests for device classes H and K for levels M, D, R, and H shall be performed through each level to determine at what levels the devices meet the RHA requirements. These RHA tests shall be performed for initial qualification and after design or process changes which may affect the RHA performance of the device.
- b. End-point electrical parameters shall be as specified in table II herein.
- c. Prior to total dose irradiation, each selected sample shall be assembled in its qualified package. It shall pass the specified group A electrical parameters in table I for subgroups specified in table II herein.
- d. For device classes H and K, the devices shall be subjected to radiation hardness assured tests as specified in MIL-H-38534 for RHA level being tested, and meet the postirradiation end-point electrical parameter limits as defined in table 1 at $T_A = +25$ °C ±5 percent, after exposure.

STANDA	RDIZED	SIZE			5962-9	91621	
MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		A		REVISION LEVE	j	SHEET	9
DESC FORM 193A SEP 87	9004708	005633	6 75	5Т 🔳	+ U \$ GOVE	NMENT PRINTING O	FFICE 1988-880-347

- e. Prior to and during total dose irradiation testing, the devices shall be biased to establish a worst case condition as specified in the radiation exposure circuit.
- f. For device classes H and K, subgroups 1 and 2 in table V, method 5005 of MIL-STD-883 shall be tested as appropriate for device construction.
- g. When specified in the purchase order or contract, a copy of the RWA delta limits shall be supplied

5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-H-38534.

6. NOTES

6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).

6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-ECC, telephone (513) 296-8527.

6.5 <u>Comments</u>. Comments on this drawing should be directed to DESC-ECC, Dayton, Ohio 45444, or telephone (513) 296-8525.

STANDARDIZED MILITARY DRAWING			size A				5962	2-91621					
	DEFE	SE ELECTRON DAYTON, C	NCS SUPPLY DHIO 45444	CE	INTER				REVIS	ONLE	VEL.	SHEET	10
DESC SEP	FORM 87	193A			900470	8	0056	337	696		÷U & QC	VERNMENT PRINT	ING OFFICE: 1888 850-

6.6 <u>One part - one part number system</u>. The one part - one part number system described below has been developed to allow for transitions between identical generic devices covered by the four major microcircuit requirements documents (MIL-N-38510, MIL-H-38534, MIL-I-38535, and 1.2.1 of MIL-STD-883) without the necessity for the generation of unique PIN's. The four military requirements documents represent different class levels, and previously when a device manufacturer upgraded military product from one class level to another, the benefits of the upgraded product were unavailable to the Original Equipment Manufacturer (OEM), that was contractually locked into the original unique PIN. By establishing a one part number system covering all four documents, the OEM can acquire to the highest class level available for a given generic device to meet system needs without modifying the original contract parts selection criteria.

Military documentation format	Example PIN under new system	Manufacturing source listing	Document <u>listing</u>
New MIL-M-38510 Military Detail Specifications (in the SMD format)	5962-XXXXXZZ(B or S)YY	QPL-38510 (Part 1 or 2)	MIL-BUL-103
New MIL-H-38534 Standardized Military Drawings	5962-XXXXXZZ(H or K)YY	GML-38534	MIL-BUL-103
New MIL-I-38535 Standardized Military Drawings	5962-XXXXXZZ(Q or V)YY	GML - 38535	MIL-BUL-103
New 1.2.1 of MIL-STD-883 Standardized Military Drawings	5962-XXXXXZZ(M)YY	MIL-BUL-103	MIL-BUL-103

6.7 Sources of supply for device classes H and K. Sources of supply for device classes H and K are listed in QML-38534. The vendors listed in QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DESC-ECC and have agreed to this drawing.

STANDAR		size A		5962-91621
MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444			REVISION LEVEL	SHEET 11
DESC FORM 193A SEP 87	90047	08 00263	38 522 🎟 🚥	GOVERNMENT PRINTING OFFICE: 1888-650-547

STANDARDIZED MILITARY DRAWING SOURCE APPROVAL BULLETIN

_ __ ~ ~

_ _ _ _ _ _ .

DATE: 91-05-15

Approved sources of supply for SMD 5962-91621 are listed below for immediate acquisition only and shall be added to QML-38534 during the next revision. QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-ECC. This bulletin is superseded by the next dated revision of QML-38534.

Standardized military drawing PIN	Vendor CAGE number	Vendor similar PIN <u>1</u> /
5962-9162101HXX	60024	PA83M/883

<u>1</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE

60024

Vendor name and address

Apex Microtechnology Corporation 5980 North Shannon Road Tucson, AZ 85741

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.

9004708 0026339 469 📟